

HIGH-DENSITY PCB TEST JACK

ABSTRACT OF THE DISCLOSURE

A printed circuit board (PCB) test jack is presented that reduces the number of PCB through-holes required for its mounting, thereby reducing signal routing interference for high-density multi-layer PCBs. The present test jack comprises a body portion arranged to interface with an external test probe, at least one surface mount conductor connected to the body portion and arrayed for attaching to corresponding surface pads on the surface of a PCB, and a signal conductor connected to the body portion. The signal conductor comprises a single through-hole pin for insertion into a corresponding single through-hole on the PCB. Using only a single through-hole pin reduces signal routing interference in the PCB when compared with a test jack employing multiple through-hole pins. Alternatively, a test jack in accordance with the present invention may employ no through-hole pins. In this case, the signal conductor is also a surface mount-type, which is connected to the body portion and arrayed for attaching to a corresponding surface pad on the surface of a PCB.

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